

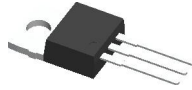
# DATA BOOK PACKAGE OUTLINE

PREVIEW

LEADFRAME EXAMPLE
4212695

DRAFTER: ANIS FAUZI	DATE: 11/22/2017		DIMENSIONS IN MILLIMETERS			
DESIGNER:	DATE:	<b>TEXAS INSTRUMENTS</b> <small>SEMICONDUCTOR OPERATIONS</small>				
CHECKER: K. SINCERBOX	DATE: 11/22/2017					
ENGINEER: AARON HENG	DATE: 11/22/2017	<b>ePOD, NEB0003F / TO-220, 3 PIN, 2.54 MM PITCH</b>				
APPROVED: EUGENE LEE & DAVID CHIN	DATE: 11/22/2017					
RELEASED: WDM	DATE: 11/20/2017					
TEMPLATE INFO: EDGE# 4218519	DATE: 03/20/2013	SCALE <b>3X</b>	SIZE <b>A</b>	<b>422XXXX</b>	REV <b>A</b>	PAGE 1 of 4

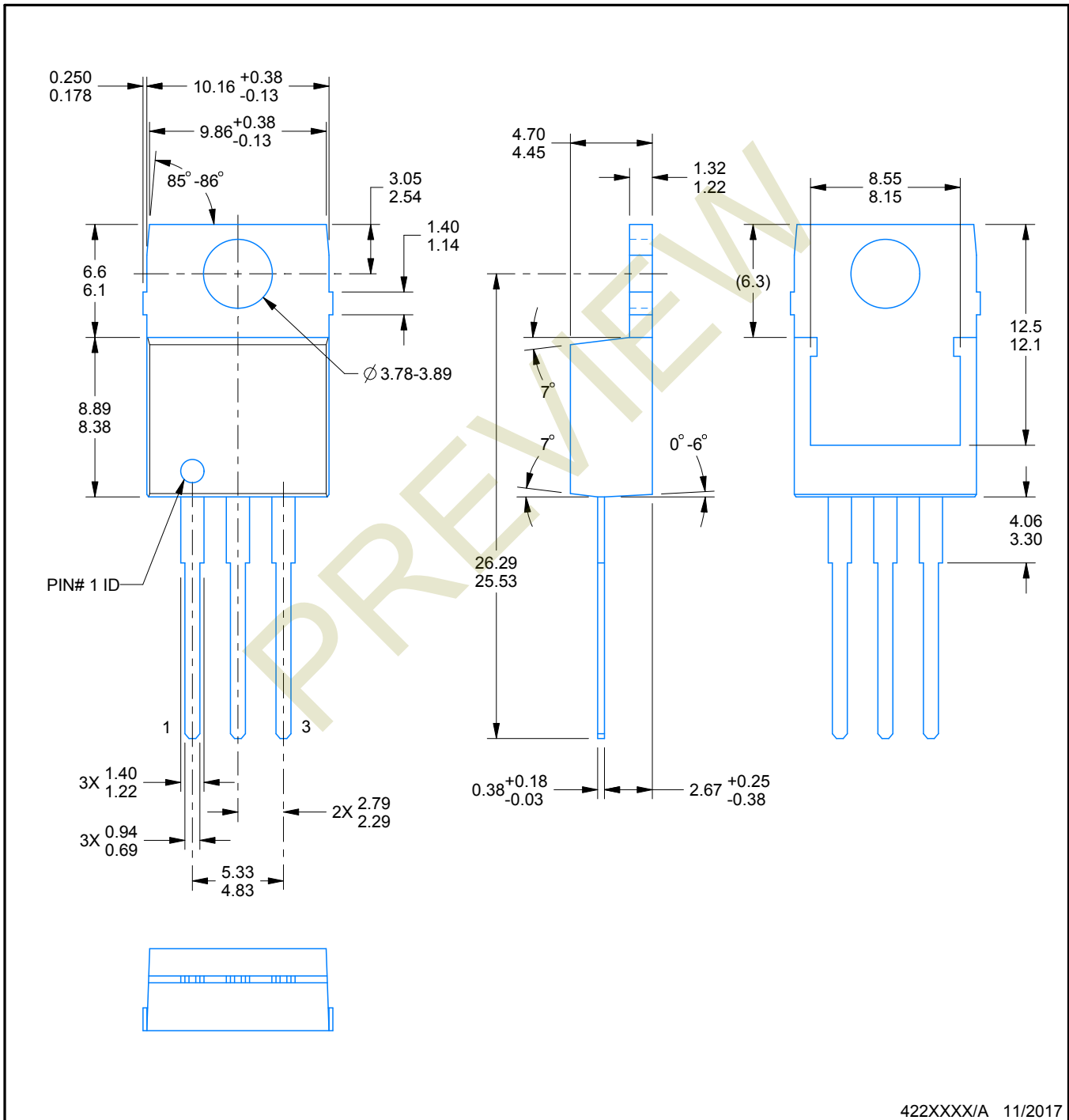
# NEB0003F



# PACKAGE OUTLINE

TO-220 - 19.65 mm max height

TRANSISTOR OUTLINE



422XXXX/A 11/2017

### NOTES:

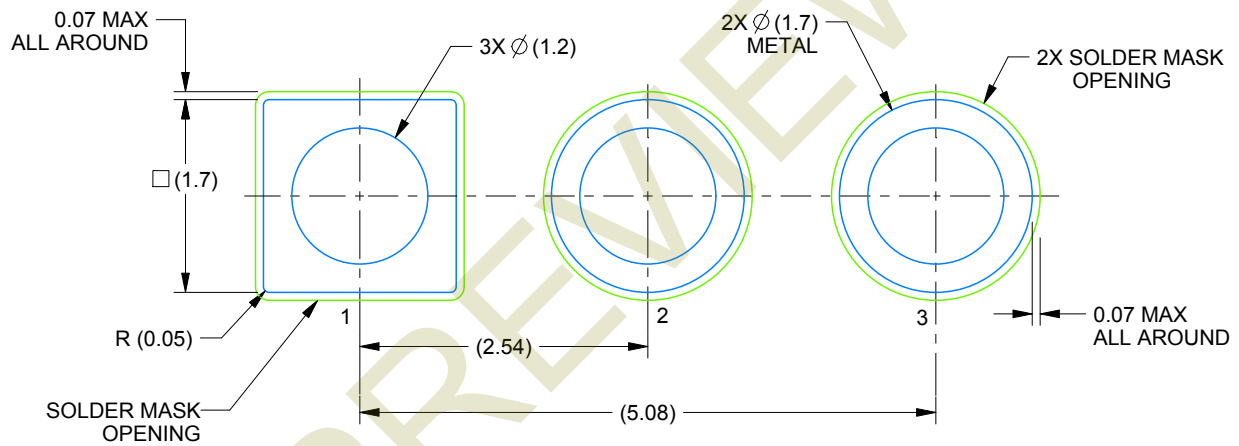
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-220.

# EXAMPLE BOARD LAYOUT

NEB0003F

TO-220 - 19.65 mm max height

TRANSISTOR OUTLINE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE:15X

422XXXX/A 11/2017

# REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	XXXXXXX	11/22/2017	AARON HENG / ANIS FAUZI

PREVIEW